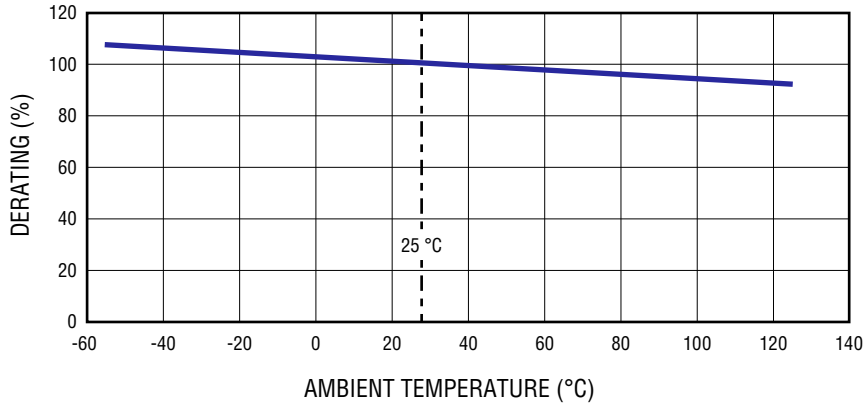
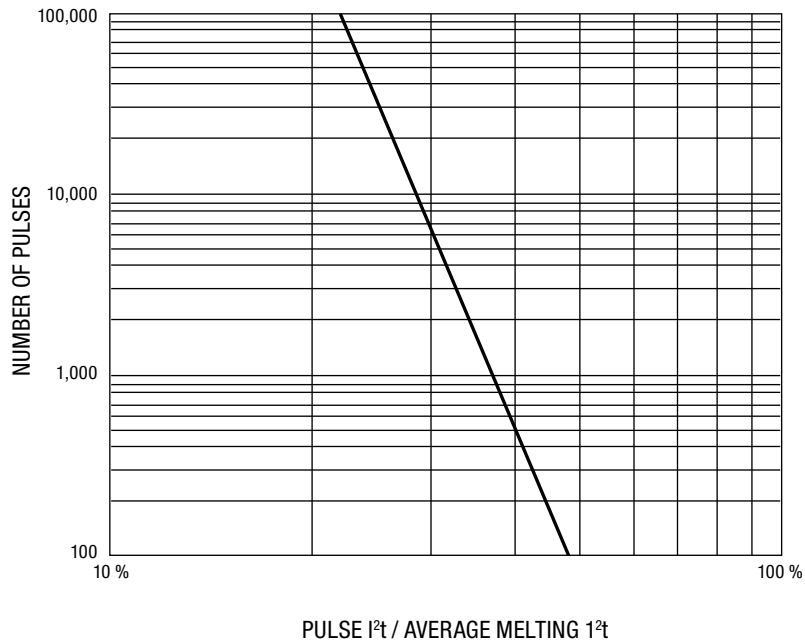


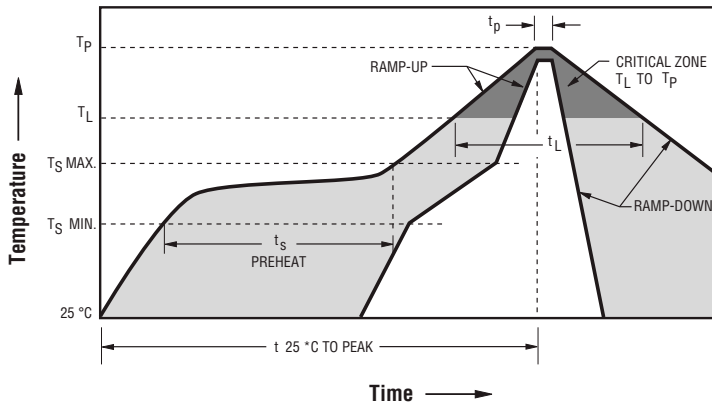
**Current Rating Thermal Derating Curve**



**Pulse Cycle Withstand Capability**



**Solder Reflow Recommendations**

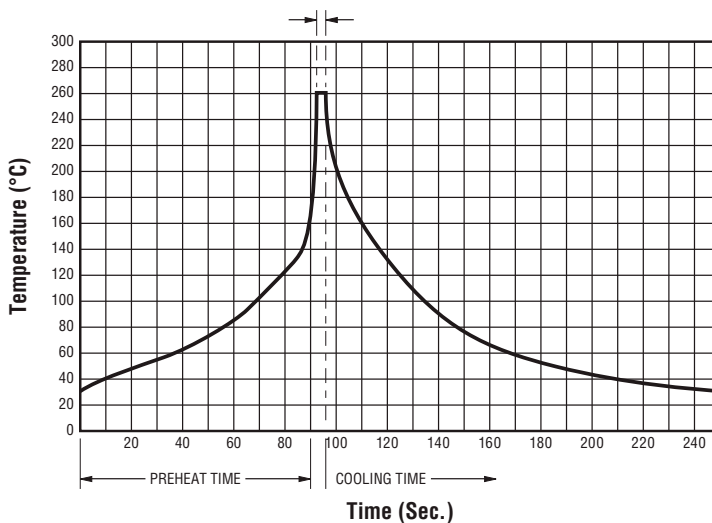


Profile Feature	Pb-Free Assembly
Preheat / Soak: Temperature Min. (T <sub>smin</sub> ) Temperature Max. (T <sub>smax</sub> ) Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	150 °C 200 °C 60~180 seconds
Ramp Up Rate (T <sub>L</sub> to T <sub>p</sub> )	3 °C / second max.
Ramp Up Rate (T <sub>smax</sub> to T <sub>L</sub> )	5 °C / second max.
Liquidous Temperature (T <sub>L</sub> ) Time (t <sub>L</sub> ) maintained above T <sub>L</sub>	217 °C 60~90 seconds
Peak Package Body Temperature (T <sub>p</sub> )	235 °C ± 5 °C
Time within 5 °C of actual peak temperature (T <sub>p</sub> )	20~30 seconds*
Ramp Down Rate (T <sub>p</sub> to T <sub>L</sub> )	6 °C / second max.
Time 25 °C to Peak Temperature	8 minutes max.
Do not exceed	240 °C

\* Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

**Solder Wave Recommendations**

Peak Temperature (Dwell Time)



Profile Feature	Pb-Free Assembly
Preheat: Temperature Max. (T <sub>smax</sub> ) Time (Min. to Max.)	150 °C 60~90 seconds
Solder Pot Temperature	260 °C max.
Solder Dwell Time	2~3 seconds

Specifications are subject to change without notice.

Users should verify actual device performance in their specific applications.

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